



ENVIRONMENTAL AND PACKAGE TESTING DATA FOR SC-70					
STRESS	SAMPLE SIZE	DEVICE HR./CYC	CONDITION	TOTAL FAILS	FAIL PERCENTAGE
BOND INT	440	235 000	200 °C + N2	0	0.00
HAST	1034	103 400	130 °C, 85 % RH	0	0.00
Power Cycle	492	6 677 096	DELTA T _J = 100 °C	0	0.00
Pressure Pot	1184	113 664	121°, 15 PSIG	0	0.00
Solder DUNK	690	2070	260 °C, 10 s	0	0.00
Solderability	165	1320	883 M2003	0	0.00
Temp. Cycle	1402	1 138 724	-55 °C to 150 °C	0	0.00